HSMMC Interface Filter and ESD Protection

RF & Protection Devices



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## BGF104C HSMMC Interface Filter and ESD Protection

## BGF104C

**Revision History: 2009-11-12, V2.0** 

Previous Version: 2009-09-14, V1.0

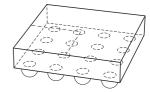
| Page | Subjects (major changes since last revision) |
|------|--|
| 4    | 3D-figure of package updated                 |
| 5    | Figure 2 updated                             |
| 6    | Footprint (Figure 3) added                   |
| 6    | Tape specification (Figure 4) added          |
| all  | Target status removed                        |



## **BGF104C**

#### **Features**

- · ESD protection and filter for High Speed Multi Media Card interface
- ESD protection according to IEC61000-4-2 for  $\pm 15$  kV contact discharge on external IOs
- 16 pin green wafer level package with SnAgCu solder balls
- RoHS and WEEE compliant package
- 500 μm solder ball pitch
- 300 μm solder ball diameter



WLP-16-3-N



#### **Description**

BGF104C is an ESD protection and filter circuit for a high speed multi media card interface. External pins are protected against ESD pulses of  $\pm 15$  kV contact discharge according to IEC61000-4-2. The wafer level package is a green leadfree package with a size of only 1.92 mm x 1.92 mm and a total height of 0.65 mm.

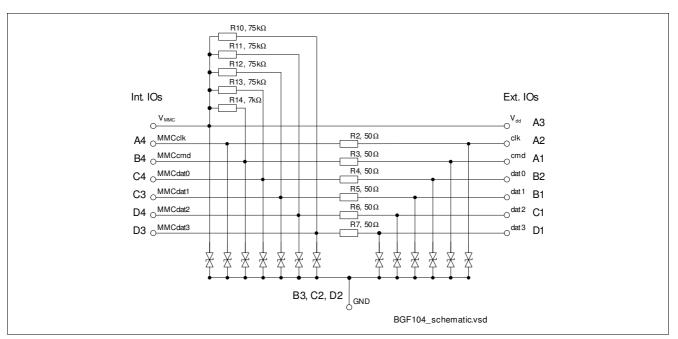


Figure 1 Schematic

| Туре    | Package  | Marking | Chip  |
|---------|----------|---------|-------|
| BGF104C | WLP-16-3 | 4C      | N0708 |

Table 1 Maximum Ratings

| Parameter   | Symbol    | Values    |   |      | Unit | Note /                |
|---|-----------|-----------|---|------|------|-----------------------|
|   |           | Min. Typ. |   | Max. |      | <b>Test Condition</b> |
| Voltage at all pins to GND  | $V_{P}$   | 0         | _ | 14   | ٧    | _                     |
| Operating temperature range   | $T_{OP}$  | -40       | _ | +85  | °C   | _                     |
| Storage temperature range   | $T_{STG}$ | -65       | _ | +150 | °C   | _                     |
| Electrostatic Discharge According to IEC                            | 61000-4-2 |           |   |      |      |                       |
| Contact discharge external pins to GND (A1, A2, A3, B1, B2, C1, D1) | $V_{ESD}$ | -15       | - | 15   | kV   | _                     |
| Contact discharge internal pins to GND (A4, B4,C3, C4, D3, D4)      | $V_{ESD}$ | -2        | - | 2    | kV   | -                     |

Table 2 Electrical Characteristics<sup>1)</sup>

| Parameter  | Symbol            | Values |      |      | Unit | Note /                |
|--|-------------------|--------|------|------|------|-----------------------|
|  |                   | Min.   | Тур. | Max. |      | <b>Test Condition</b> |
| Resistors $R_2 \dots R_7$                        | R <sub>27</sub>   | 40     | 50   | 60   | Ω    | _                     |
| Resistors $R_{10} \dots R_{13}$                  | R <sub>1013</sub> | 52.5   | 75   | 97.5 | kΩ   | _                     |
| Resistor R <sub>14</sub>                         | R <sub>14</sub>   | 4.9    | 7    | 9.1  | kΩ   | _                     |
| Line capacitance, each line to GND <sup>2)</sup> | $C_{T}$           | _      | 16   | 20   | pF   | V = 0 V               |
| Reverse current of ESD protection diodes         |                   |        |      |      |      |                       |
| $I_R = 3 \text{ V}$                              | $I_{R}$           | _      | 5    | 100  | nA   | _                     |
| I <sub>R</sub> = 14 V                            |                   |        | 0.1  | 10   | μΑ   |                       |

<sup>1)</sup> at  $T_{A} = 25 \, ^{\circ}\text{C}$ 

### **Package Outlines**

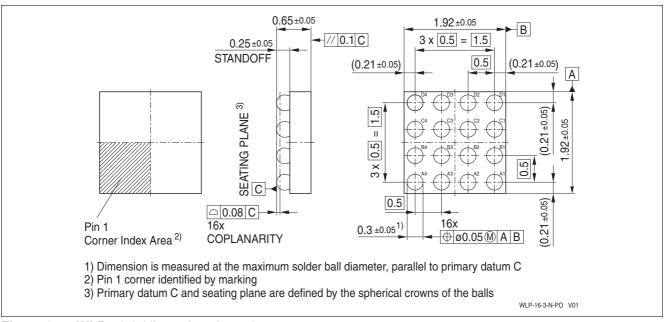


Figure 2 WLP-16-3 (dimensions in mm)

<sup>2)</sup> Without line coupling by Resistors  $R_7$  -  $R_{11}$ 

## **Footprint**

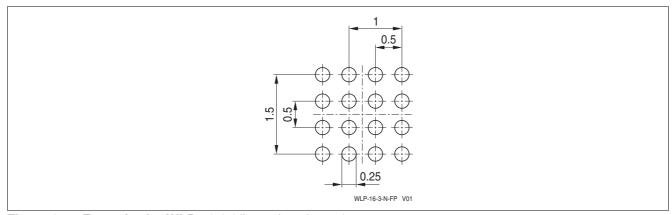


Figure 3 Footprint for WLP-16-3 (dimensions in mm)

## Tape and reel specification

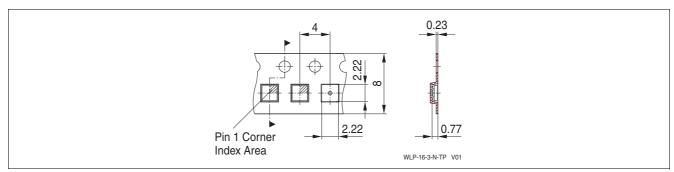


Figure 4 Tape for WLP-16-3 (dimensions in mm)

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